



External convective jumping-droplet condensation on a flat plate



Patrick Birbarah^a, Nenad Miljkovic^{a,b,*}

^a Department of Mechanical Science and Engineering, University of Illinois, Urbana, IL 61801, United States

^b International Institute for Carbon Neutral Energy Research (WPI-I2CNER), Kyushu University, 744 Moto-oka, Nishi-ku, Fukuoka 819-0395, Japan

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ABSTRACT

Water vapor condensation is vital to many natural and industrial processes such as building environmental control, power generation, and water desalination. Jumping-droplet condensation of water has recently been shown to have a 10X heat transfer enhancement compared to state-of-the-art filmwise condensation due to the removal of condensate at much smaller length scales ($\sim 1 \mu\text{m}$) than what is capable with gravitational shedding ($\sim 1 \text{mm}$). However, the efficient removal of jumping droplets can be limited by droplet return to the surface due to gravity, entrainment in bulk convective vapor flow, and entrainment in local condensing vapor flow. If used appropriately, convective condensation has the potential to entrain droplets, hence impeding their return to the surface. In this work, a comprehensive model of external convective jumping-droplet condensation on a superhydrophobic flat plate has been developed for constant heat flux boundary conditions. Boundary layer analysis was used to model the vapor flow over the external plate with condensation modeled as a vapor suction at the wall. The model was used to analyze the effects of jumping droplet size ($1 < R_d < 100 \mu\text{m}$), condensation heat flux ($0 < q < 10 \text{W/cm}^2$), initial jumping location along the plate ($10 \text{cm} < x_0 < 5 \text{m}$), free stream velocity ($1 < U_f < 30 \text{m/s}$), and plate inclination ($0\text{--}360^\circ$), on droplet trajectory and overall heat transfer performance. Analysis of droplet trajectories revealed that the total distance traveled by jumping droplets along the plate ranged from millimeters to meters, while jumping heights were limited to less than a centimeter for the parameters considered. In addition, multiple-droplet coalescence, along with multi-jump droplet dynamics were analyzed, helping to explain a previously observed multi-hop process, and providing a potential pathway to generate larger effective trajectories along the plate. This work provides a comprehensive physical model of the external convective jumping-droplet condensation process, offers guidelines for the design of jumping-droplet systems to maximize heat transfer and minimize flooding, and develops a theoretical framework for the analysis of future convective jumping-droplet condensation processes important to more industrially relevant internal flow situations such as channels and tubes.

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1. Introduction

Water vapor condensation, whether industrially driven or occurring in nature, is a critical process for the sustainability of ecosystems and advancement of economies. Due to the reduced energy barrier for vapor-to-liquid nucleation, condensation preferentially occurs on high surface energy substrates [1], forming a thermally-insulating liquid blanket, termed filmwise condensation [2]. In an effort to shed the liquid layer and enhance heat transfer, engineers and researchers have devised techniques for creating non-wetting surfaces to enable dropwise [3] or jumping-droplet condensation [4], whereby non-wetting droplets shed due to grav-

ity at millimetric length scales or spontaneously jump away from the surface at micrometric length scales [5], respectively. Specifically, jumping-droplet condensation, whereby microdroplets ($\sim 10\text{--}100 \mu\text{m}$) condensing and coalescing on suitably designed superhydrophobic surfaces undergo surface-to-kinetic energy transfer and result in the merged droplet jumping away from the surface [5–10], has recently been shown to have a 10X heat transfer enhancement compared to state-of-the-art filmwise condensing surfaces [11–20]. A number of works have since fabricated superhydrophobic nanostructured surfaces to achieve spontaneous droplet removal [21–31] for a variety of applications including self-cleaning [32–34], thermal diodes [33,35], anti-icing [36–39], vapor chambers [40], electrostatic energy harvesting [41–43], and heat transfer enhancement [44–55].

However, the efficient removal of jumping droplets along with the heat transfer enhancement can be limited by droplet return

* Corresponding author at: 105 S. Mathews Avenue, Mechanical Engineering Laboratory, Room 2136, Urbana, IL 61801, United States.

E-mail address: nmiljkov@illinois.edu (N. Miljkovic).

Nomenclature

ρ_l	density of liquid water	Re_x	Reynolds number based on x
ρ_v	density of water vapor	Re_d	Reynolds number based on droplet radius
ν_v	kinematic viscosity of water vapor	Re_G	Reynolds number based on velocity gradient
μ_v	dynamic viscosity of water vapor	Re_L	Reynolds number at $x = L$
μ_l	dynamic viscosity of liquid water	Bo	bond number
h_{fg}	latent heat of vaporization of water	We	Weber number
γ	surface tension of water (liquid–vapor interface)	Ma	Mach number
\vec{g}	gravitational field	Ca	Capillary number
q	heat Flux	δ	boundary layer thickness
T_{sat}	saturation temperature of the vapor	η	non dimensional similarity variable
T_w	wall temperature at a given location	φ	dimensional stream function
\dot{m}_c	mass flux of condensate	f	non-dimensional stream function
w	width of the plate	τ_w	wall shear stress
ψ	angle of inclination of plate (CCW)	$\bar{\tau}$	average wall shear stress
ψ_{crit}	critical angle of inclination (CCW)	d	distance of interest of shear stress analysis
L	distance traveled by the droplet	F_p	force on the plate per unit length
h	maximum jumping height of the droplet (horizontal plate)	$F_{p, film}$	force on the plate from laminar filmwise convective condensation
x	horizontal coordinate axis (fixed)	\vec{F}_D	drag force
y	vertical coordinate axis (fixed)	\vec{F}_G	gravitational force
x^1	coordinate axis tangent to the plate	\vec{F}_{SL}	Saffman lift force
y^1	coordinate axis perpendicular to the plate	ϕ_S	Saffman multiplier
\vec{j}^1	unitary vector in the y^1 direction	F_σ	adhesion force between liquid and solid
R	rotation matrix	$F_{SL,x}$	x -component of Saffman force
V_w	velocity of the vapor at the wall, perpendicular to surface	$F_{SL,y}$	y -component of Saffman force
U_f	free stream velocity	g_{x^1}	projection of gravity along x^1
\vec{V}_{rel}	relative velocity vector between vapor flow and droplet	g_{y^1}	projection of gravity along y^1
\vec{V}_f	velocity vector of the vapor flow	x_0	initial position of droplet in the x direction
\vec{V}_d	velocity vector of droplet	x_0^1	initial position of droplet in the x^1 direction
u	horizontal velocity of the vapor flow	y_0^1	initial position of droplet in the y^1 direction
v	vertical velocity of the vapor flow	R_d	droplet radius
u^1	flow velocity in the x^1 direction	m	mass of droplet
u_d^1	droplet velocity in the x^1 direction	$R_{d,0}$	initial droplet radius in a multihop process
v_d	velocity of the droplet in the y direction	t	time
v_{rel}	relative velocity in the y direction	C	proportionality constant
u_{rel}	relative velocity in the x direction	$\Delta\theta^{app}$	apparent contact angle hysteresis
$u_{d,0}^1$	initial velocity of the droplet in the x^1 direction	θ_e^{app}	apparent equilibrium contact angle
$u_{d,end}^1$	final velocity of the droplet in the x^1 direction	θ_r^{app}	apparent receding contact angle
$v_{d,0}^1$	initial velocity of the droplet in the y^1 direction	θ_a^{app}	apparent advancing contact angle
$v_{d,end}^1$	final velocity of the droplet in the y^1 direction	u_c	horizontal velocity of the flow at the midpoint of the sessile droplet's vertical projection
θ	angle formed by the vertical and horizontal relative velocities (u and v)	y_c	vertical coordinate of the midpoint of the sessile droplet's vertical projection
C_D	drag coefficient	A_p	projected face area of the sessile droplet
		i	arbitrary index of a jump in a multihop process

to the surface due to (1) gravitational force (2) entrainment in a bulk convective vapor flow, and (3) entrainment in the local condensing vapor flow toward the surface [40,56]. The first two return mechanisms (gravity and bulk vapor flow) can be mitigated with suitable geometric design of the macroscale condensing surface and vapor supply. However, the third return mechanism (local vapor flow) is more difficult to eliminate due to the need to conserve mass of the condensing vapor flowing towards the surface. Although previous studies have experimentally characterized the effects of gravitational return, [57,58] further study of local vapor flow entrainment on droplet return and methods to limit this process are needed.

One avenue to enhance droplet removal after jumping is by exploiting the fact that jumping droplets attain a positive charge ($\sim +10fC$) after departing the superhydrophobic surface due to electric-double-layer charge separation at the coating-droplet

interface [43]. This discovery has allowed for the development of electric-field-enhanced (EFE) condensation, whereby an external electric field was used to enhance the removal of jumping droplets from a radial (tube) condensing surface by counteracting the three droplet return mechanisms described above [59]. Through the elimination of droplet return, a heat transfer enhancement of 20X was experimentally demonstrated, compared to state-of-the-art filmwise condensing surfaces.

While the removal of the droplets by external electric fields offers a method remove condensate, practical difficulties exist. For example, the need for energized external electrodes presents critical safety concerns. Furthermore, the need to remove the condensate from the external electrode has not been addressed. Lastly, the added complexity associated with the design and manufacture of EFE system equates to higher probability of failure once integrated into real life applications.

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